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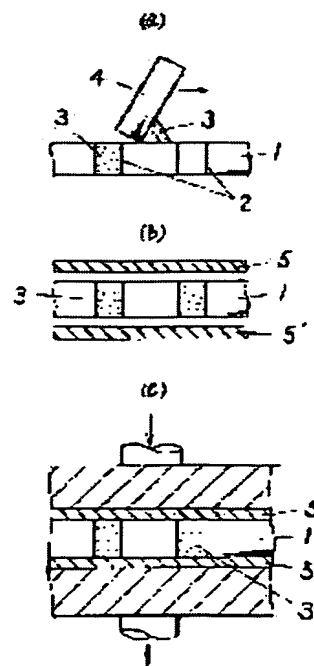
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## (54) DIFFUSED JUNCTION METHOD FOR COPPER OR COPPER ALLOY AT LOW TEMPERATURE, AND MANUFACTURE OF CONDUCTIVE PASTE AND MANUFACTURE WIRING BOARD USING THE SAME

(57)Abstract:

PURPOSE: To provide the manufacture method for a multilayer wiring board excellent in an electrical characteristic capable of joining copper or copper alloys at a low temperature, further a simple work method is used by applying this theory.

CONSTITUTION: Metals are joined together by heating and pressurizing the metals at 170° or over, providing a conductive paste layer whose main composing elements are conductive powder consisting of the thin film layer of a noble metal, an oxidized film remover layer or copper, or their alloys and activator on a surface whose at least one side is copper or a copper alloy. Further, by applying this connecting theory, after rubbing conductive paste 3 whose main composing elements are conductive powder consisting of a noble metal, copper or their alloys and activator, into a hole 2 made in the prescribed part of an insulating adhesive material layer 1, the insulating adhesive material layer 1 is placed between copper foils 5 and 5', and a multilayer wiring board is manufactured by heating and pressurizing it at 170° C or over.



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